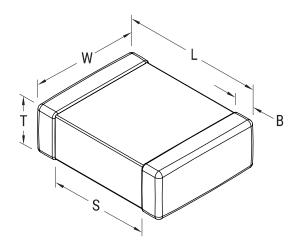


C0402C161K2TAC7411

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SMD Comm X8G HT150C, Ceramic, 160 pF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0402, 0.3 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.06 mg
Shelf Life	78 Weeks
MSL	1

Dimensions		Sp
Chip Size	0402	Ca
L	1mm +/-0.05mm	Me
W	0.5mm +/-0.05mm	Tol
т	0.5mm +/-0.05mm	Vo
S	0.3mm MIN	Die
В	0.3mm +/-0.1mm	Ter
		Тог

Packaging Specifications

Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	50000

Specifications	
Capacitance	160 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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